,03257$17 127,&($1' ',6&/$,0(5

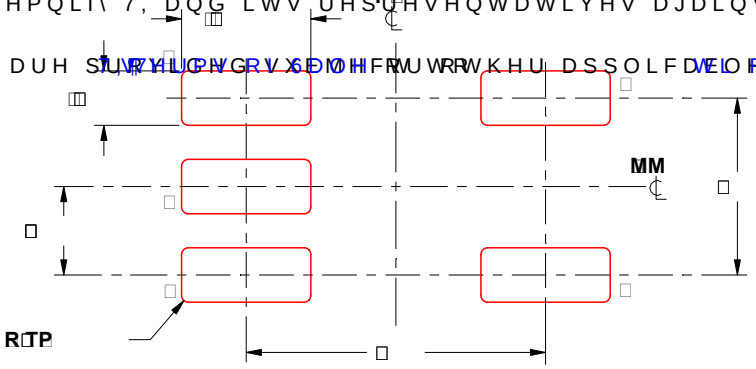
MA OTINE TRANITOR

7, 3529,'(6 7(&+1,&$/ $1' 5(/,$%,/,7< '7 ,1&/8',1* '7 6+((76 '(6,*1 5(6285&(6 ,1&/8',1* 5()
'(6,*16 $33/,&$7,21 25 27+(5 '(6,*1 $'9,&(:(% 722/6 6$)(7< ,1)250$7,21 $1' 27+(5 5(6285&(6
$1' :,7+ $//)$8/76 $1' ',6&/$,06 $// :$55$17,(6 (;35(66 $1' ,03/,(' ,1&/8',1* :,7+287 /,0,7$7,21
,03/,(' :$55$17,(6 2) 0(5&+17%,/,7<)25 $ 3$57,&8/$5 385326(25 121 ,1)5,1*(0(17 2) 7+,5'
3$57< ,17(//(&78$/ 3523(57< 5,*+76

7KHVH UHVRXUFHV DUH LQWHQGHG IRU VNLOOHG GHYHORSHUV ZLWK GHVLJQ LQ WKH DSSOLFDWLRQ WKDW \RX DUH GHVLJQLQJ
7, SURGXFWV IRU \RXU DSSOLFDWLRQ GHVLJQLQJ YDOLGDWLQJ DQG WHVWLQJ \RXU DS
VWDQGDUGV DQG DQ\ RWKHU VDIHW\ VHFXULW\ UHJXODWRU\ RU RWKHU UHTXLUHPHQWV

7KHVH UHVRXUFHV DUH VXEMHFW WR FKDQJH ZLWKRXW QRWLFH 7, JUDQWV \RX SHUPLVVL
DSSOLFDWLRQ WKDW XVHV WKH 7, SURGXFWV GHVFULEHG LQ WKH UHVRXUFH 2WKHU UHSUL
LV JUDQWHG WR DQ\ RWKHU 7, LQWHOOHFWXDO SURSHUW\ RU WR DQ\ RWKHU WHFKQRORJ SDUW\
ZLOO IXOO\ LQGHPQLI\ 7, DQG LWV UHSUHVHQWDWLYHV DJDLQVW DQ\ FODLPV GDPDJHV F
UHVRXUFHV

7,¶V SURGXFWV DUH SURYLGHG VXEMHFW WR 7, WHUPV RI VDOH RU RWKHU DSSOLFDEOH WHUPV DYDLODEOH HLWKHU RQ LWV



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NOTE continud

asr cuttin aprturs it trapoidal alls and roundd cornrs a or ttr past rlas IPC a a altrnat
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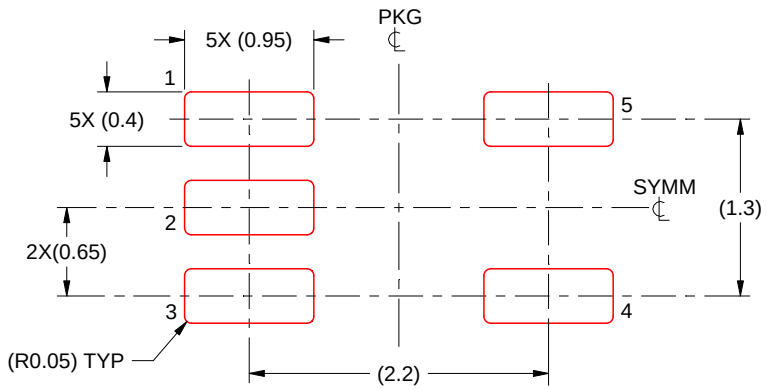
oard ass sit a a dirnt rcondations or stncil dsin



SOLDER PASTE EXAMPLE
BASED ON 0.125 THICK STENCIL
SCALE:18X

4214834/C 03/2023

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
7. Board assembly site may have different recommendations for stencil design.

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